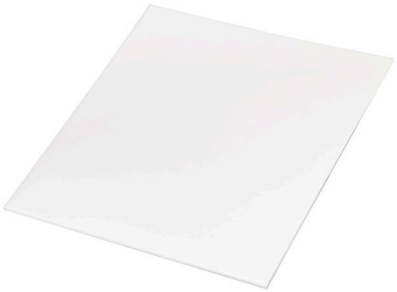
SERIES: AF100 | DESCRIPTION: THERMAL PAD

FEATURES

- 1.0 W/m*K thermal conductivity
- naturally tacky
- silicone free
- electrical isolation
- sizes to match CUI Devices peltier footprints



RoHS

SPECIFICATIONS

parameter	test method/conditions/description	min	typ	max	units
material	non-silicone elastomer				
color	white				
thickness	ASTM D374		0.5		mm
specific gravity	ASTM D792		2.1		g/cc
hardness	ASTM D2240	60		90	shore 00
tensile strength	ASTM D412		30		psi
operating temperature		-40		120	°C
dielectric breakdown voltage	ASTM D149	200			Vac/mil
dielectric constant (1 MHz)	ASTM D150		4.0		
volume resistivity	ASTM D257		$3^* 10^{13}$		Ω*cm
thermal conductivity	ASTM D5470		1.0		W/m*K
thermal resistance	1 mm, 40 psi; ASTM D5470		1.1		°C*in²/W
compression ratio	1 mm, 40 psi		30		%
flammability rating	UL94V-0				
RoHS	yes				

PART NUMBER KEY

AF100 - XXXX 05

Base Number

Footprint Size (mm):
10x10 = 1010 15x15 = 1515
15x30 = 1530 20x20 = 2020
20x40 = 2040 26.25x50 = 2650
30x12 = 3012 30x30 = 3030
31.25x30 = 3130 40x40 = 4040
41.25x45 = 4145 50x50 = 5050
70x70 = 7070

REVISION HISTORY

rev.	description	date
1.0	initial release	11/02/2018
1.01	brand update	03/23/2020
1.02	modified material	04/06/2021
1.03	logo, datasheet style update	08/05/2022

The revision history provided is for informational purposes only and is believed to be accurate.